

PCB LAYOUT * - COMPONENT VIEW

TECHNICAL CHARACTERISTICS

MATERIAL
INSULATOR: LCP
FLAMABILITY RATING: UL94-V0
COLOR: BLUE
CONTACT MATERIAL: PHOSPHORE BRONZE
CONTACT TYPE: STAMPED
CONTACT PLATING: UNDERPLATE 1.27 to 2.54 μm Ni
CONTACT AREA 0.76 μm Gold
SOLDER TAIL AREA 2.54 to 5.08 μm Matt Tin
SHIELDING: BRASS MATT TIN PLATED

ENVIRONMENTAL
OPERATING TEMPERATURE: -20 up to +85°C
COMPLIANCE: RoHS & LEAD FREE AS PER DIRECTIVE 2002/95/EC
HALOGEN FREE COMPLIANT AS PER IEC 61249-2-21

ELECTRICAL
CURRENT RATING:
- PIN 1 & PIN 4 (Vbus & corresponding ground PIN) 1.8A Max
- OTHER PINS 0.25 A Max
WORKING VOLTAGE: 30Vac
DIELECTRIC WITHSTANDING VOLTAGE: 100Vac/min
INSULATION RESISTANCE: > 100M Ω
CONTACT RESISTANCE:
- PIN 1 & PIN 4: 30m Ω Max
- OTHER PINS: 50m Ω Max


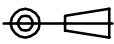
STANDARD
CERTIFIED: E323964 / MODEL NUMBER 692122030100

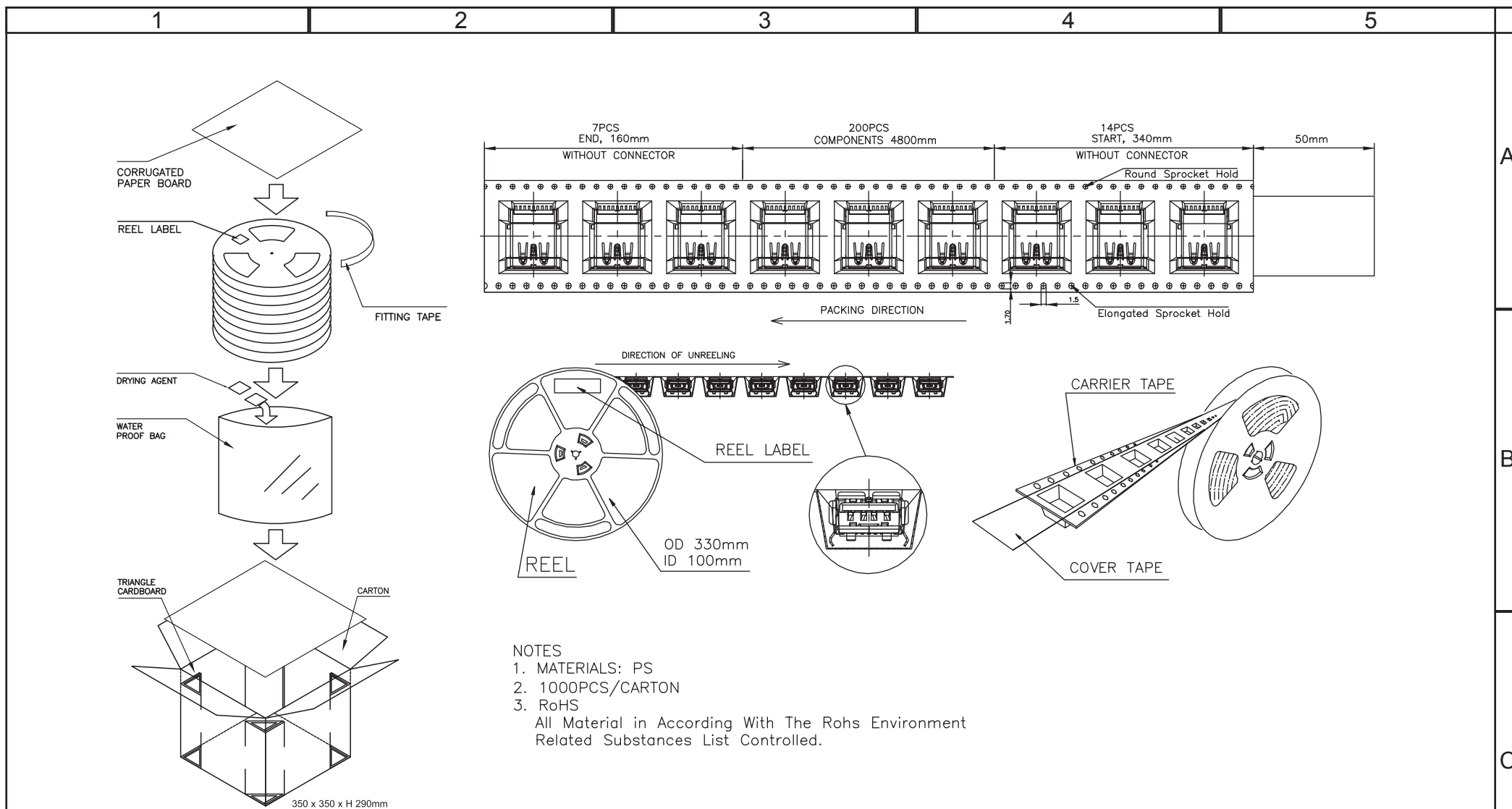
MECHANICAL
INSERTION FORCE: 35.0N Max
EXTRACTION FORCE: 10.0N min
QUALITY CLASS: 5000 MATING CYCLES

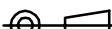

SOLDERING
WAVE & REFLOW PROCESS AS PER JEDEC J-STD-020D

PACKAGING
TAPE & REEL

* NOTE: THE RECOMMENDED PCB LAYOUT IS FOR AN OPTIMIZED RETENTION FORCE OF CONNECTOR ON PCB BUT IT IMPLIES INSERTION FORCE THAT A LOT OF PICK AND PLACE MACHINES ARE NOT ABLE TO HANDLE. THEREFORE IT MIGHT BE NECESSARY TO DRILL BIGGER HOLES FOR THE CLIPS. PLEASE CHECK THIS CAREFULLY.

RoHS Compliant				PROJECTION:	GENERAL TOLERANCE .X = ± 0.2 .XX = ± 0.15		DESCRIPTION: USB 3.0 HORIZONTAL TYPE A	SIZE A4
G	F	E	D					
	17-SEP-13	10-SEP-13	09-NOV-11		APPROVAL: RJ	UNIT: MM	WERI PART NO: 692 122 030 100	
	CHARACTERISTICS	DIM UPDATE	STENCIL					
	QL	QL	GG					
	21-SEP-11	NOTE	GG					
	10-MAY-11	UL	GG					
	04-AUG-10	PDF	JP					
REV	DATE	FILE	BY					



RoHS Compliant							
G				<div>PROJECTION:</div> <div></div>	<div>GENERAL TOLERANCE</div> <div>.X = \pm 0.2</div> <div>.XX = \pm 0.15</div>	<div></div> <div>WÜRTH ELEKTRONIK</div>	
F							
E							
D							
C				APPROVAL: RJ	UNIT: MM	DESCRIPTION: USB 3.0 HORIZONTAL TYPE A	SIZE A4
B					SCALE:		
A					SHEET: 2/3	WERI PART NO: 692 122 030 100	
REV	DATE	FILE	BY		DRAW: JOE		

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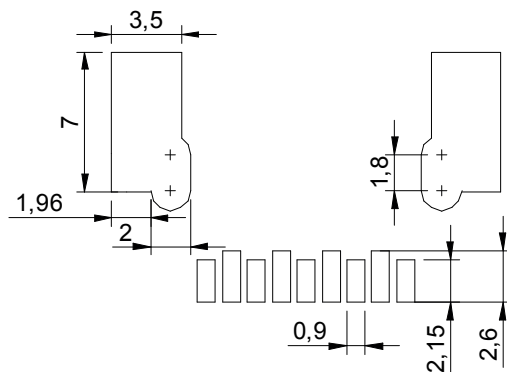
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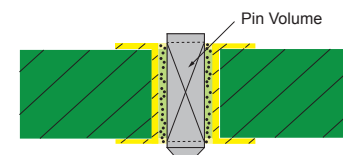
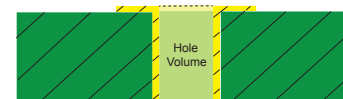
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Stencil information for Through Hole Reflow soldering



STENCIL LAYOUT * - COMPONENT VIEW

PCB cross section



Free volume for solder paste

Theoretical Formula for Through Hole pins

Volume of the stencil aperture = (Hole volume - Pin volume) x 2

or

Volume of solder paste = (Hole volume - Pin volume) x 2

Stencil

Stencil Thickness: 150 µm

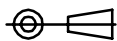
PCB

PCB thickness: 1.6mm

RoHS Compliant

* NOTE: SEE PCB LAYOUT PAGE 1/3 FOR MISSING DIMENSIONS

PROJECTION:



GENERAL TOLERANCE

.X = ± 0.2

.XX = ± 0.15



APPROVAL: RJ

UNIT: MM

SCALE:

SHEET: 3/3

DRAW: JOE

DESCRIPTION: USB 3.0 HORIZONTAL TYPE A

WERI PART NO: 692 122 030 100

SIZE

A4